DECLARATION OF INVENTORSHIP AND POWER OF ATTORNEY FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

2251189

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and fo which a patent is sought on the invention entitled: Method of Manufacturing Semiconductor Packages The specification of which				
	was filed on			
	under Applic	ation Serial No.	and was	
	amended on			
	(if applicable)			
including the clain	ns, as amended by and duty to disclose to	y amendment referred to a	s of the above-identified specification above. n which is material to Patentability as	
inventor's certifica	ate listed below and	have also identified below	any foreign application(s) for patent or w any foreign application for patent or cation on which priority is claimed.	
Prior Foreign Ap	plication(s)			
APPLICAT	ION NUMBER	COUNTRY	FILING DATE	
I hereby claim the	e benefit under 35 U	JSC §120 of any United	States application(s) listed below and	

I hereby claim the benefit under 35 USC §120 of any United States application(s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of 35 USC § 112, I acknowledge the duty to disclose to the Office information which is material to patentability as defined in CFR § 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

APPLICATION NUMBER FILING DATE

STATUS

(Patented, Pending, Abandoned)

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

Address all correspondence to: ANDERSON KILL & OLICK, P.C.

1251 Avenue of Americas New York, NY 10020 U. S. A. I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 USC 1001, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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Residence	Citizenship		
Post Office Address			
Full name of fourth joint inventor, if any			
Inventor's Signature	Date		
Residence	Citizenship		
Post Office Address			
Full name of fifth joint inventor, if any			
Inventor's Signature	Date		
Residence	Citizanchin		
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